



## SSC8621GN4

### N and P-Channel Enhancement Mode Power MOSFET

#### ➤ Features

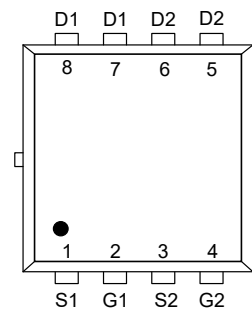
##### N-Channel

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
20V	$\pm 12V$	9m $\Omega$ @4.5V	38A
		12m $\Omega$ @2.5V	

##### P-Channel

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
-20V	$\pm 12V$	13m $\Omega$ @-4.5V	-33A
		17m $\Omega$ @-2.5V	

#### ➤ Pin configuration

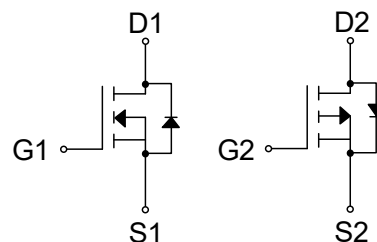


**PDFN3.3X3.3-8L (Top View)**

#### ➤ Description

The SSC8621GN4 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

**100% UIS +  $\Delta V_{DS}$  +  $R_g$  Tested!**



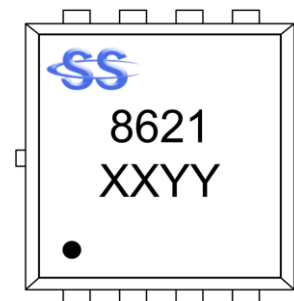
**Pin Configuration**

#### ➤ Applications

- PWM Applications
- Load Switch
- DC-DC Converters
- Wireless Chargers

#### ➤ Ordering Information

Device	Package	Shipping
SSC8621GN4	PDFN3.3X3.3-8L	5000/Reel



**Marking**

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-to-Source Voltage		$V_{\text{DSS}}$	20	-20	V
Gate-to-Source Voltage		$V_{\text{GSS}}$	$\pm 12$	$\pm 12$	V
Continuous Drain Current <sup>a</sup>	$T_A=25^{\circ}\text{C}$	$I_{\text{D}}$	38	-33	A
	$T_A=100^{\circ}\text{C}$		19	-17	A
Pulsed Drain Current <sup>b</sup>		$I_{\text{DM}}$	150	-130	A
Power Dissipation <sup>a</sup>		$P_{\text{DSM}}$	2.6	2.7	W
Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		$I_{\text{AS}}$	9.5	-9.5	A
Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		$E_{\text{AS}}$	23	23	mJ
Power Dissipation <sup>c</sup>	$T_A=25^{\circ}\text{C}$	$P_{\text{D}}$	20	21	W
	$T_A=100^{\circ}\text{C}$		8	8.3	W
Operation junction temperature		$T_{\text{J}}$	-55 to 150	-55 to 150	$^{\circ}\text{C}$
Storage temperature range		$T_{\text{STG}}$	-55 to 150	-55 to 150	$^{\circ}\text{C}$

**➤ Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	N-Channel	P-Channel	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	48	47	$^{\circ}\text{C/W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	6.25	6	

Note:

- The value of  $R_{\theta\text{JA}}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_{\text{D}}$  is based on  $T_{\text{J(MAX)}}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

**➤ N-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

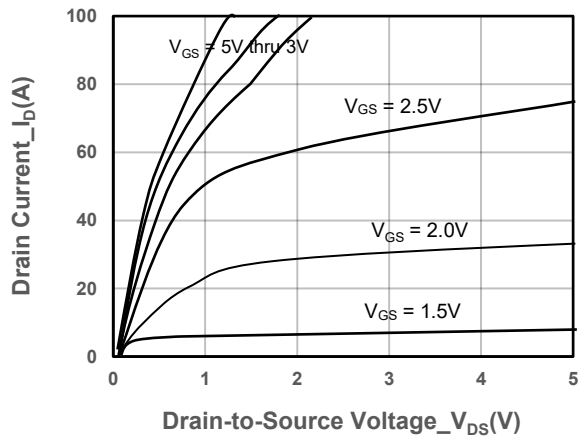
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	0.5	0.8	1.2	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A		9	14	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 10A		12	17	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5A		22		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A		0.6	1.3	V
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, f = 1MHz		2.5		Ω
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		1195		pF
Output Capacitance	C <sub>OSS</sub>			182		
Reverse Transfer Capacitance	C <sub>RSS</sub>			160		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 15A		14		nC
Gate to Source Charge	Q <sub>GS</sub>			3		
Gate to Drain Charge	Q <sub>GD</sub>			3.4		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 15A, R <sub>GEN</sub> = 3Ω		8.4		ns
Rise Time	T <sub>r</sub>			17.7		
Turn-off Delay Time	T <sub>D(OFF)</sub>			26.8		
Fall Time	T <sub>f</sub>			10.5		

**➤ P-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

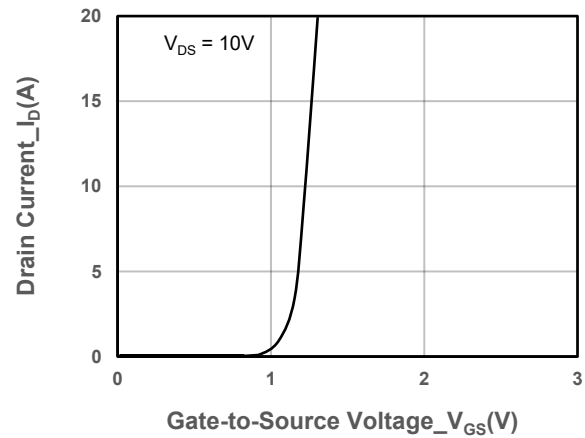
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-0.4	-0.8	-1.2	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A		13	19	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -5A		17	24	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -5A		15		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A		-0.7	-1.3	V
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, f = 1MHz		9.5		Ω
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz		2468		pF
Output Capacitance	C <sub>OSS</sub>			193		
Reverse Transfer Capacitance	C <sub>RSS</sub>			352		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -7A		18.5		nC
Gate to Source Charge	Q <sub>GS</sub>			4.5		
Gate to Drain Charge	Q <sub>GD</sub>			4.2		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -7A, R <sub>GEN</sub> = 3Ω		7.8		ns
Rise Time	T <sub>r</sub>			34.4		
Turn-off Delay Time	T <sub>D(OFF)</sub>			49.4		
Fall Time	T <sub>f</sub>			11		



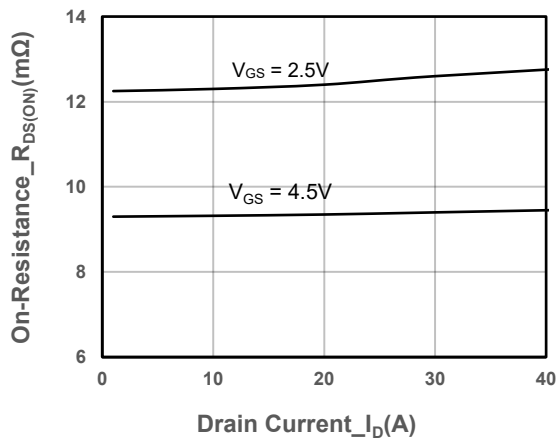
## ➤ N-Channel Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



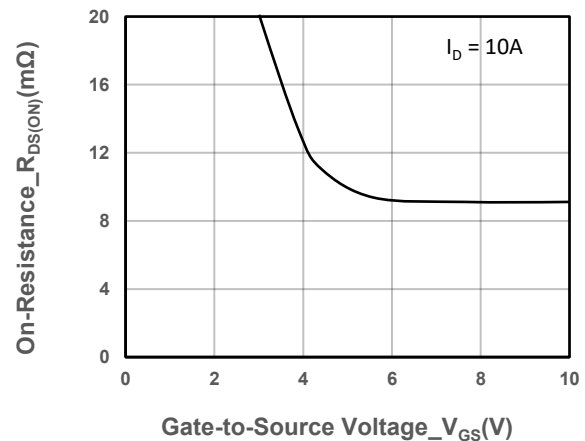
Output Characteristics



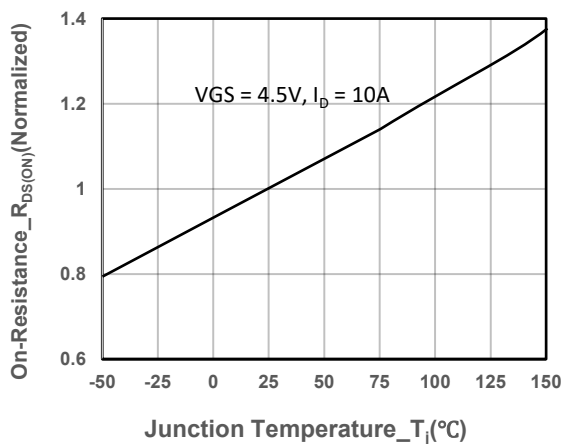
Transfer Characteristics



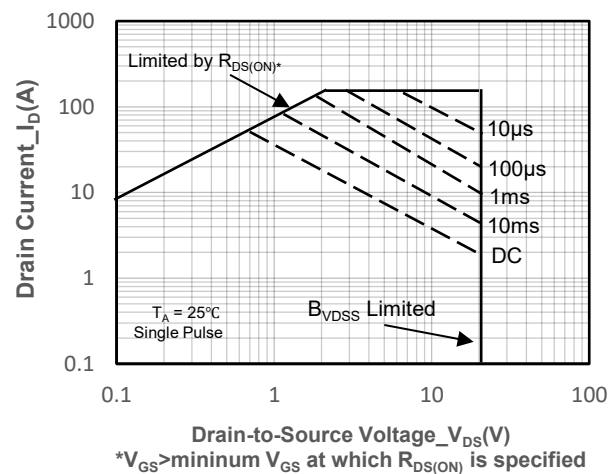
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



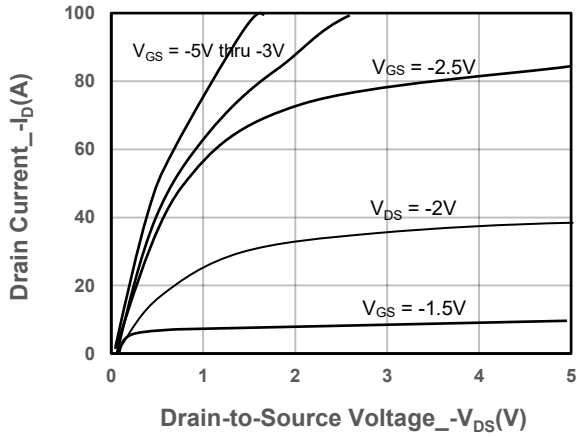
On-Resistance vs. Junction Temperature



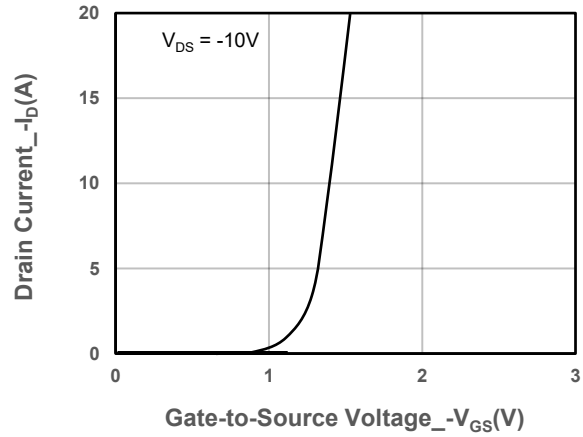
Safe Operating Area vs. Junction-to-Ambient



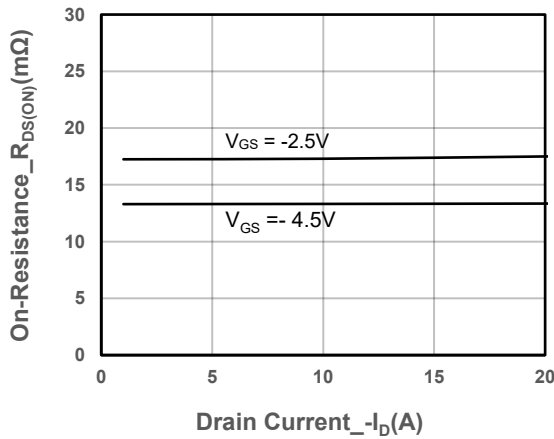
## ➤ P-Channel Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



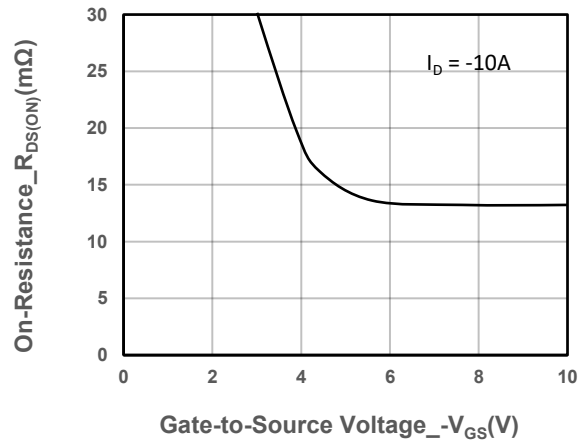
Output Characteristics



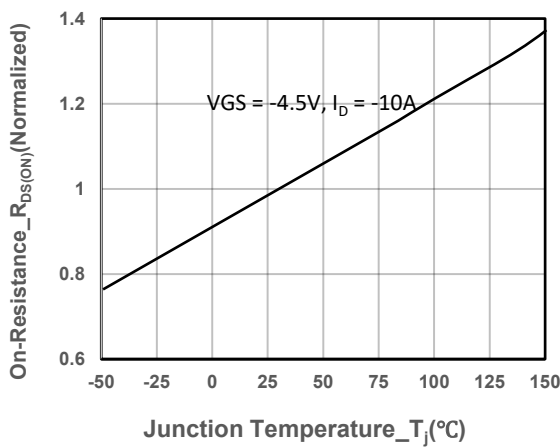
Transfer Characteristics



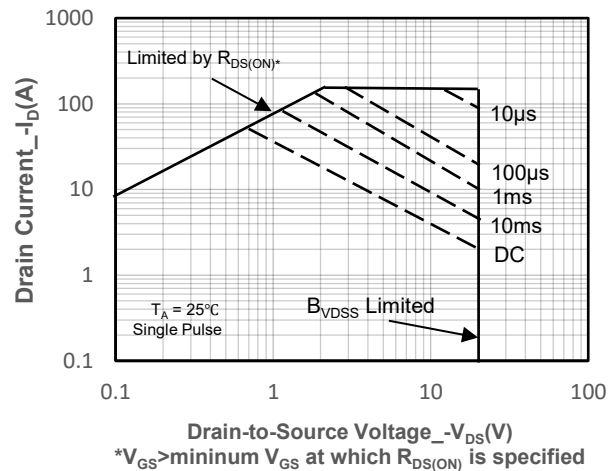
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

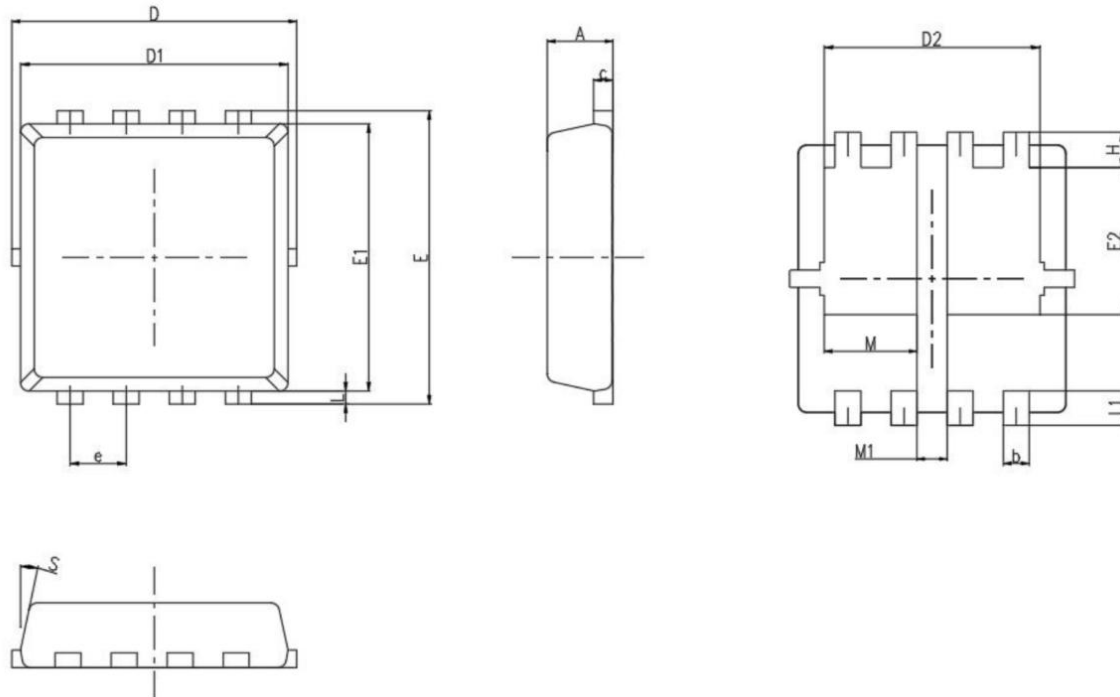


On-Resistance vs. Junction Temperature



Safe Operating Area vs. Junction-to-Ambient

## ➤ Package Information



Symbol	MILL IMETER		
	Min	Nom	Max
A	0.60	0.75	0.90
b	0.25	0.30	0.35
c	0.10	0.20	0.30
D	3.00	3.20	3.45
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.10	3.30	3.50
E1	2.90	3.05	3.20
E2	1.55	1.75	1.95
e	0.65BSC		
H	0.20	0.40	0.57
L	0.06	0.10	0.20
L1	0.30	0.40	0.55
S	10°	12°	14°
M	0.95	1.05	1.15
M1	0.4BSC		



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